

September 2009

# 4N38M, H11D1M, H11D2M, H11D3M, MOC8204M High Voltage Phototransistor Optocouplers

### **Features**

- High voltage:
  - MOC8204M, BV<sub>CER</sub> = 400V
  - H11D1M, H11D2M, BV<sub>CER</sub> = 300V
  - H11D3M, BV<sub>CER</sub> = 200V
- High isolation voltage:
  - 7500 V<sub>AC</sub> peak, 1 second
- Underwriters Laboratory (UL) recognized File # E90700, Volume 2
- IEC 60747-5-2 approved (ordering option V)

### **Applications**

- Power supply regulators
- Digital logic inputs
- Microprocessor inputs
- Appliance sensor systems
- Industrial controls

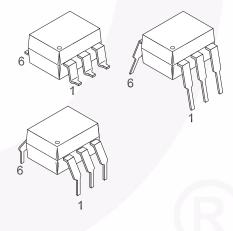
### **General Description**

The 4N38M, H11DXM and MOC8204M are phototransistor-type optically coupled optoisolators. A gallium arsenide infrared emitting diode is coupled with a high voltage NPN silicon phototransistor. The device is supplied in a standard plastic six-pin dual-in-line package.

### **Schematic**

# ANODE 1 6 BASE 5 COLLECTOR N/C 3

### **Package Outlines**



### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Device	Value	Units
TOTAL DEV	ICE			
T <sub>STG</sub>	Storage Temperature	All	-40 to +150	°C
T <sub>OPR</sub>	Operating Temperature	All	-40 to +100	°C
T <sub>SOL</sub>	Lead Solder Temperature (Wave Solder)	All	260 for 10 sec	°C
P <sub>D</sub>	Total Device Power Dissipation @ T <sub>A</sub> = 25°C	All	260	mW
	Derate Above 25°C		3.5	mW/°C
EMITTER				
I <sub>F</sub>	Forward DC Current <sup>(1)</sup>	All	80	mA
V <sub>R</sub>	Reverse Input Voltage <sup>(1)</sup>	All	6.0	V
I <sub>F</sub> (pk)	Forward Current – Peak (1µs pulse, 300pps) <sup>(1)</sup>	All	3.0	Α
$P_{D}$	LED Power Dissipation @ T <sub>A</sub> = 25°C <sup>(1)</sup>	All	150	mW
Derate Above 25°C			1.41	mW/°C
DETECTOR				
P <sub>D</sub>	Power Dissipation @ T <sub>A</sub> = 25°C	All	300	mW
	Derate linearly above 25°C		4.0	mW/°C
V <sub>CER</sub>	Collector to Emitter Voltage <sup>(1)</sup>	MOC8204M	400	V
		H11D1M, H11D2M	300	
		H11D3M	200	
		4N38M	80	
V <sub>CBO</sub>	Collector Base Voltage <sup>(1)</sup>	MOC8204M	400	V
		H11D1M, H11D2M	300	
		H11D3M	200	
		4N38M	80	
V <sub>ECO</sub>	Emitter to Collector Voltage <sup>(1)</sup>	H11D1M, H11D2M, H11D3M, MOC8204M	7	V
I <sub>C</sub>	Collector Current (Continuous)	All	100	mA

### Note:

1. Parameters meet or exceed JEDEC registered data (for 4N38M only).

## Electrical Characteristics (T<sub>A</sub> = 25°C unless otherwise specified.)

### **Individual Component Characteristics**

Symbol	Characteristic	Test Conditions	Device	Min.	Тур.*	Max.	Unit
EMITTER	•					1	'
V <sub>F</sub>	Forward Voltage <sup>(2)</sup>	I <sub>F</sub> = 10mA	All		1.15	1.5	V
$\frac{\Delta V_F}{\Delta T_A}$	Forward Voltage Temp. Coefficient		All		-1.8		mV/°C
$BV_R$	Reverse Breakdown Voltage	I <sub>R</sub> = 10μA	All	6	25		V
СЈ	Junction Capacitance	$V_F = 0V, f = 1MHz$	All		50		pF
		$V_F = 1V, f = 1MHz$			65		pF
I <sub>R</sub>	Reverse Leakage Current <sup>(2)</sup>	V <sub>R</sub> = 6V	All		0.05	10	μA
DETECTO	R					1	'
BV <sub>CER</sub>	Breakdown Voltage	$R_{BE} = 1M\Omega, I_{C} = 1.0mA, I_{F} = 0$	MOC8204M	400			V
	Collector to Emitter <sup>(2)</sup>		H11D1M/2M	300			
			H11D3M	200			1
BV <sub>CEO</sub>		No RBE, I <sub>C</sub> = 1.0mA	4N38M	80			1
BV <sub>CBO</sub>	Collector to Base <sup>(2)</sup>	$I_C = 100 \mu A, I_F = 0$	MOC8204M	400			V
			H11D1M/2M	300			
			H11D3M	200			
			4N38M	80	\		
$BV_{EBO}$	Emitter to Base	$I_E = 100 \mu A, I_F = 0$	4N38M	7			V
$BV_{ECO}$	Emitter to Collector	$I_E = 100 \mu A, I_F = 0$	All	7	10		V
I <sub>CER</sub>	Leakage Current	$V_{CE} = 300V, I_F = 0, T_A = 25^{\circ}C$	MOC8204M			100	nA
	Collector to Emitter <sup>(2)</sup> ( $R_{BE} = 1M\Omega$ )	$V_{CE} = 300V, I_F = 0, T_A = 100^{\circ}C$				250	μA
		$V_{CE} = 200V, I_F = 0, T_A = 25^{\circ}C$	H11D1M/2M			100	nA
		V <sub>CE</sub> = 200V, I <sub>F</sub> = 0, T <sub>A</sub> = 100°C				250	μA
		$V_{CE} = 100V, I_F = 0, T_A = 25^{\circ}C$	H11D3M			100	nA
		V <sub>CE</sub> = 100V, I <sub>F</sub> = 0, T <sub>A</sub> = 100°C				250	μA
I <sub>CEO</sub>		No R <sub>BE</sub> , $V_{CE}$ = 60V, $I_F$ = 0, $T_A$ = 25°C	4N38M			50	nA

### **Transfer Characteristics** ( $T_A = 25$ °C Unless otherwise specified.)

Symbol	Characteristics	Test Conditions	Device	Min.	Тур.*	Max.	Units
EMITTER							
CTR	Current Transfer Ratio, Collector to	$I_F$ = 10mA, $V_{CE}$ = 10V, $R_{BE}$ = 1M $\Omega$	H11D1M/2M/3M, MOC8204M	2 (20)			mA (%)
	Emitter	I <sub>F</sub> = 10mA, V <sub>CE</sub> = 10V	4N38M	2 (20)			
V <sub>CE(SAT)</sub>	Saturation Voltage <sup>(2)</sup>	$I_F$ = 10mA, $I_C$ = 0.5mA, $R_{BE}$ = 1M $\Omega$	H11D1M/2M/3M, MOC8204M		0.1	0.40	V
		I <sub>F</sub> = 20mA, I <sub>C</sub> = 4mA	4N38M			1.0	
SWITCHING TIMES							
t <sub>ON</sub>	Non-Saturated Turn-on Time	$V_{CE}$ = 10V, $I_{CE}$ = 2mA, $R_L$ = 100 $\Omega$	All		5		μs
t <sub>OFF</sub>	Turn-off Time		All		5		μs

<sup>\*</sup>All Typical values at  $T_A = 25$ °C

### Note:

2. Parameters meet or exceed JEDEC registered data (for 4N38M only).

# DC Electrical Characteristics (Continued) (T<sub>A</sub> = 25°C unless otherwise specified.)

### **Isolation Characteristics**

Symbol	Characteristic	Test Conditions	Device	Min.	Тур.*	Max.	Units
V <sub>ISO</sub>	Isolation Voltage	f = 60Hz, t = 1 sec.	All	7500			V <sub>AC</sub> PEAK
R <sub>ISO</sub>	Isolation Resistance	V <sub>I-O</sub> = 500 VDC	All	10 <sup>11</sup>			Ω
C <sub>ISO</sub>	Isolation Capacitance	f = 1MHz	All		0.2		pF

<sup>\*</sup>All Typical values at  $T_A = 25$ °C

## **Safety and Insulation Ratings**

As per IEC 60747-5-2, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Symbol	Parameter	Min.	Тур.	Max.	Unit
	Installation Classifications per DIN VDE 0110/1.89 Table 1				
	For Rated Main Voltage < 150Vrms		I-IV		
	For Rated Main voltage < 300Vrms		I-IV		
	Climatic Classification		55/100/21		
	Pollution Degree (DIN VDE 0110/1.89)		2		
CTI	Comparative Tracking Index	175			
V <sub>PR</sub>	Input to Output Test Voltage, Method b, V <sub>IORM</sub> x 1.875 = V <sub>PR</sub> , 100% Production Test with tm = 1 sec, Partial Discharge < 5pC	1594			V <sub>peak</sub>
	Input to Output Test Voltage, Method a, V <sub>IORM</sub> x 1.5 = V <sub>PR</sub> , Type and Sample Test with tm = 60 sec, Partial Discharge < 5pC	1275			V <sub>peak</sub>
V <sub>IORM</sub>	Max. Working Insulation Voltage	850			$V_{peak}$
V <sub>IOTM</sub>	Highest Allowable Over Voltage	6000			$V_{peak}$
	External Creepage	7			mm
	External Clearance	7			mm
	Insulation Thickness	0.5			mm
RIO	Insulation Resistance at Ts, V <sub>IO</sub> = 500V	10 <sup>9</sup>			Ω

### Typical Performance Curves

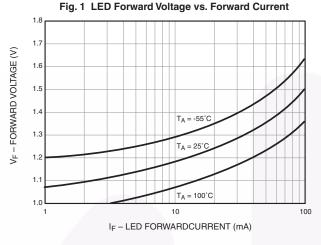


Fig. 2 Normalized Output Characteristics

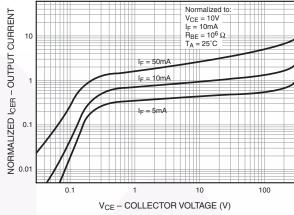


Fig. 3 Normalized Output Current vs. LED Input Current

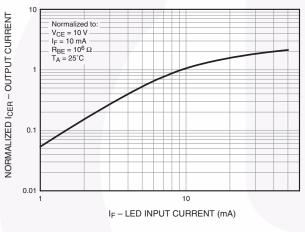


Fig. 4 Normalized Output Current vs. Temperature

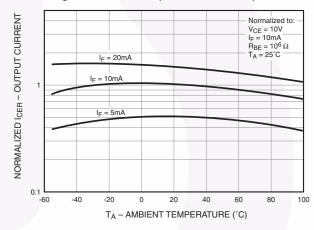


Fig. 5 Normalized Dark Current vs. Ambient Temperature

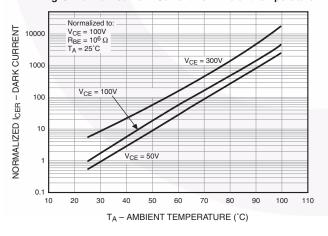
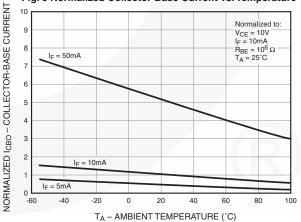
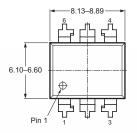


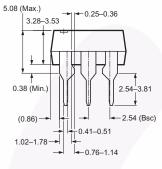
Fig. 6 Normalized Collector-Base Current vs. Temperature

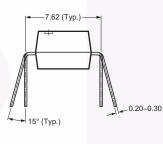


### **Package Dimensions**

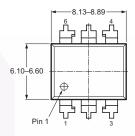
### **Through Hole**

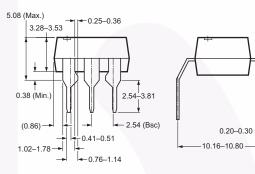




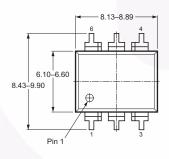


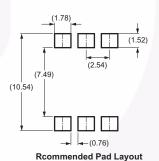
### 0.4" Lead Spacing

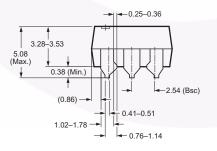


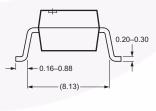


### **Surface Mount**







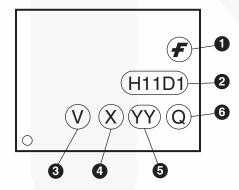


**Note:** All dimensions in mm.

# 查询"MOC8204M"供应商 Ordering Information

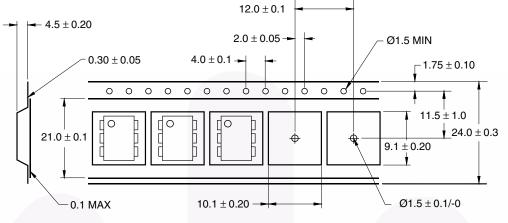
Option	Order Entry Identifier (Example)	Description
No option	H11D1M Standard Through Hole Device (50 units per tub	
S	S H11D1SM Surface Mount Lead Bend	
SR2	H11D1SR2M	Surface Mount; Tape and Reel
Т	H11D1TM	0.4" Lead Spacing
V	H11D1VM	VDE 0884
TV	H11D1TVM	VDE 0884, 0.4" Lead Spacing
SV	H11D1SVM	VDE 0884, Surface Mount
SR2V	H11D1SR2VM	VDE 0884, Surface Mount, Tape and Reel

# **Marking Information**



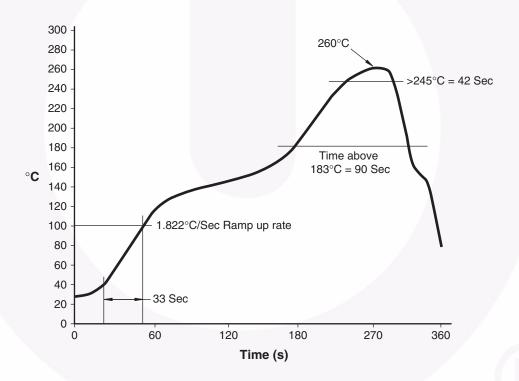
Definitions					
1	Fairchild logo				
2	Device number				
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)				
4	One digit year code, e.g., '7'				
5	Two digit work week ranging from '01' to '53'				
6	Assembly package code				

### **Carrier Tape Specification**



User Direction of Feed -----

### **Reflow Profile**





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### Definition of Terms

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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.				
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